Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L-0501-04** DATE: 1/28/2005

Product Affected: IDT74SSTVF16859NL
IDT74SSTVF16859NLG

Date Effective: 2/28/2005

MEANS OF DISTINGUISHING CHANGED DEVICES:

☐ Product Mark
☐ Back Mark
☒ Date Code "0510" and later
☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment:: ☒ Yes ☐ No

Samples: See attachment

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☒ Material
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☐ Other

To standardize the exposed bottom pad dimensions at different assembly locations for NL/NLG56 packages.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for reliability/qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: L-0501-04

PCN Type:	Standardize exposed bottom pad dimension
Data Sheet Change:	There is change in Moisture Sensitive Level from level 3 to level 1.
Detail of Change:	NL/NLG56 package is assembled at different assembly locations. This PCN is being issued to notify customer that the exposed bottom pad dimensions will be standardized as follow:

Description	From	To
Exposed Bottom Pad	6.0 x 4.8 mm	5.1 x 4.4 mm
Inside Die Pad	5.0 x 6.2 mm	4.65 x 5.35 mm

This change will be implemented on all products assembled at ASAT with date code (0510) or later. There will be a change in moisture sensitive level from level 3 to level 1.

The affected products are as follow:

IDT74SSTVF16859NL	IDT74SSTVF16859NLG

Qualification Plan: P04-09-02
Test Vehicle: IDT74SSTVN16859
Qualification Test Plan and Results:

Test Descriptions	Test Methods	Sample size /# Fails	Test results NLG56
Moisture Sensitive Level	J-STD-020B	90/0	90/0
Physical Dimensions	JESD22-B100-B	5/0	5/0